

ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS AND POLISHING METHOD

The polishing apparatus includes: a polishing table configured to support a polishing pad having a polishing surface; a rotatable head body having a pressing surface; a retainer ring configured to press the polishing surface and rotatable together with the head body; a rotary ring; a stationary ring; and local-load exerting devices each configured to apply a local load to the stationary ring. The local-load exerting devices include a first pressing member and a second pressing member coupled to the stationary ring. The first pressing member is arranged at an upstream side of the retainer ring in a moving direction of the polishing surface, and the second pressing member is arranged at a downstream side of the retainer ring in the moving direction of the polishing surface.

FIG. 2